

**CHIMEI**

a step up

**Non-flame Retardant PC Alloy WONDERLOY® PC-860**

Product Description: PC/ASA, UL 746C f1, UV Stabilized

Properties	ISO Test Method	Test Condition	Unit	PC-860
<b>Melt Flow Index</b>	1133	260°C×2.16KG	ml/10 min	7
		260°C×5KG		22
<b>Spiral flow</b>	CHIMEI	260°C,2mm,V:50%,P:50%	cm	38
<b>Mass Density</b>	1183	23 °C	g/cm <sup>3</sup>	1.13
<b>Tensile Strength</b>	527	50 mm/min, yield	MPa	53
		50 mm/min, break		55
<b>Tensile Elongation</b>	527	50 mm/min	%	110
<b>Flexural Strength</b>	178	2 mm/min	MPa	80
<b>Flexural Modulus</b>		2 mm/min	GPa	2.2
<b>Izod Impact Strength</b>	180/1A	23°C, Notched	KJ/m <sup>2</sup>	45
		-30°C, Notched		15
<b>Charpy Impact Strength</b>	179	23°C, Notched	KJ/m <sup>2</sup>	45
		-30°C, Notched		15
<b>Vicat Softening Temp.</b>	306	50°C/hr;1KG	°C	137
		50°C/hr;5KG		122
<b>Heat Distortion Temp.</b>	75/A	1.8MPa, unannealed	°C	104
<b>Dielectric Constant</b>	IEC 60250	1MHz	--	3.1
<b>Volume Resistivity</b>	IEC 60093	--	Ohm X m	1E+16
<b>Surface Resistivity</b>	IEC 60093	--	Ohm	1E+16
<b>Coefficient of Linear Thermal Expansion</b>	11359	-	-	8*10 <sup>-5</sup>
<b>Flammability</b>	-	UL-94	-	1.5mm HB
<b>Weatherability</b>	-	UL 746C	-	f1
<b>Mold Shrinkage</b>	294-4	-	%	0.4~0.6
<b>Symbol</b>	1043	-	-	>PC+ASA<